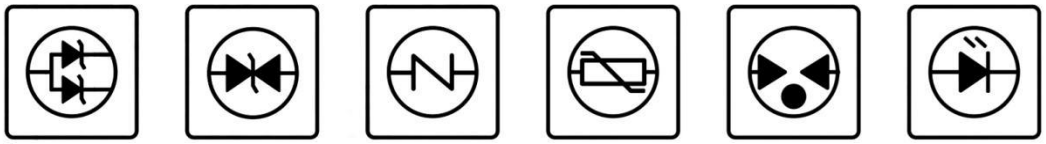
MSKSEMI
SEMICONDUCTOR



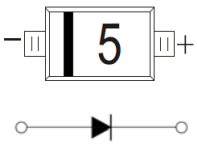
ESD TVS TSS MOV GDT PLED

Product data sheet

www.msksemi.com

SOD-523

MARKING: 5



RB751S-40 Schottky barrier Diode

FEATURES

- Small surface mounting type
- Low reverse current and low forward voltage
- High reliability

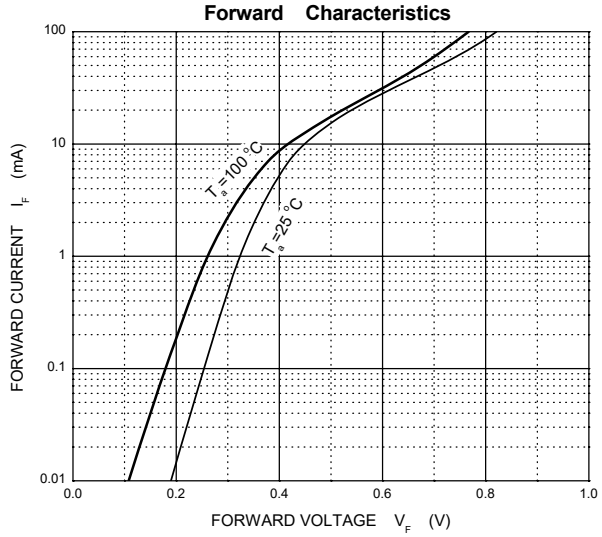
Maximum Ratings and Electrical Characteristics, Single Diode @Ta=25℃

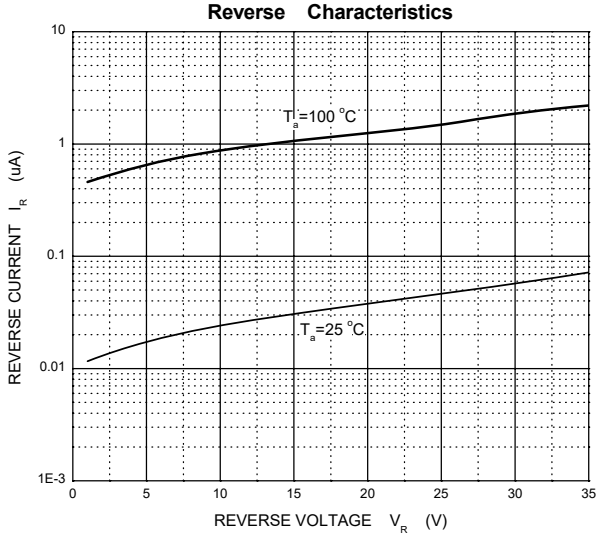
Parameter	Symbol	Limit	Unit
Peak reverse voltage	V_{RM}	40	V
DC reverse voltage	V_R	40	V
Mean rectifying current	I_O	30	mA
Non-repetitive Peak Forward Surge Current@t=8.3ms	I_{FSM}	200	mA
Power dissipation	P_D	150	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	667	℃/W
Junction temperature	T_j	125	℃
Storage temperature	T_{stg}	-55~+150	℃

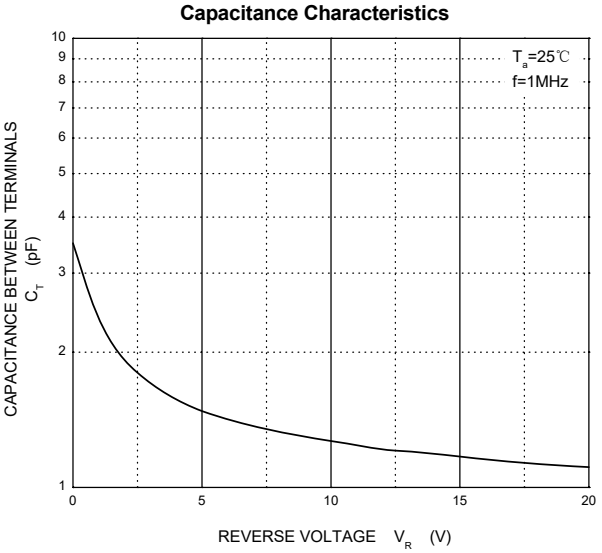
Electrical Ratings @Ta=25℃

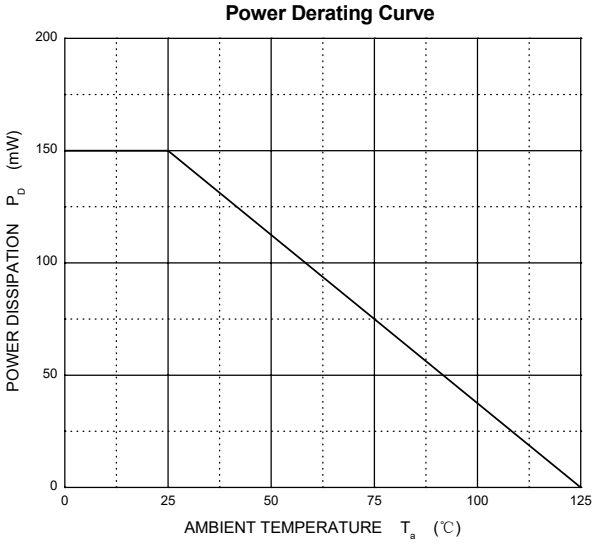
Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Reverse voltage	$V_{(BR)}$	40			V	I_R=1mA
Forward voltage	V_F	0.20		0.37	V	I_F=1mA
Reverse current	I_R	0.01		0.5	μA	V_R=30V
Capacitance between terminals	C_T	0.5	2	10	pF	V_R=1V,f=1MHZ

Typical Characteristics

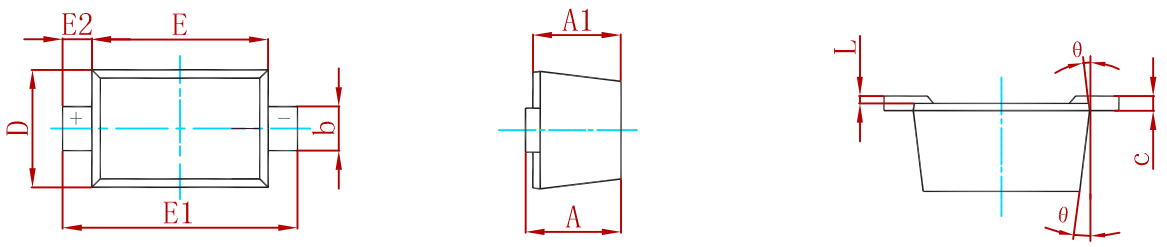






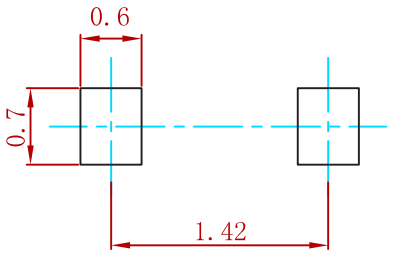


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° REF	

Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
RB751S-40	SOD-523	3000

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